

SOT950-1

plastic thin fine-pitch ball grid array package; 208 balls; body
15 x 15 x 0.7 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	TFBGA208
Package type industry code	TFBGA208
Package style descriptive code	TFBGA (thin fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	14-6-2006

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	14.9	-	15	15.1	mm
E	package width	14.9	-	15	15.1	mm
A	seated height	[tbd]	-	1.2	1.2	mm
A ₂	package height	0.6	-	0.7	0.8	mm
n ₂	actual quantity of termination	-	-	208	-	



2. Package outline

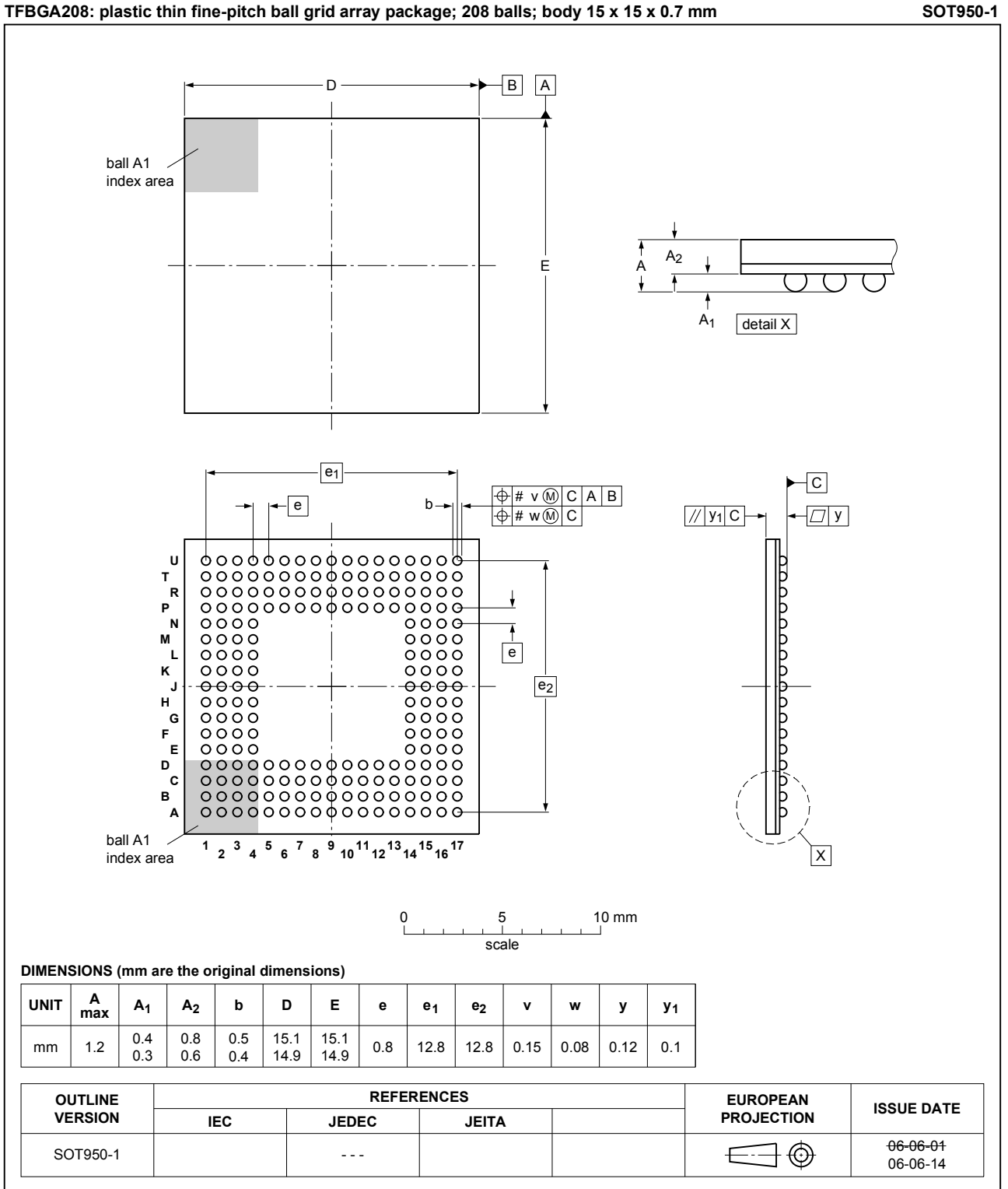


Fig. 1. Package outline TFBGA208 (SOT950-1)

3. Soldering

Footprint information for reflow soldering of TFBGA208 package

SOT950-1

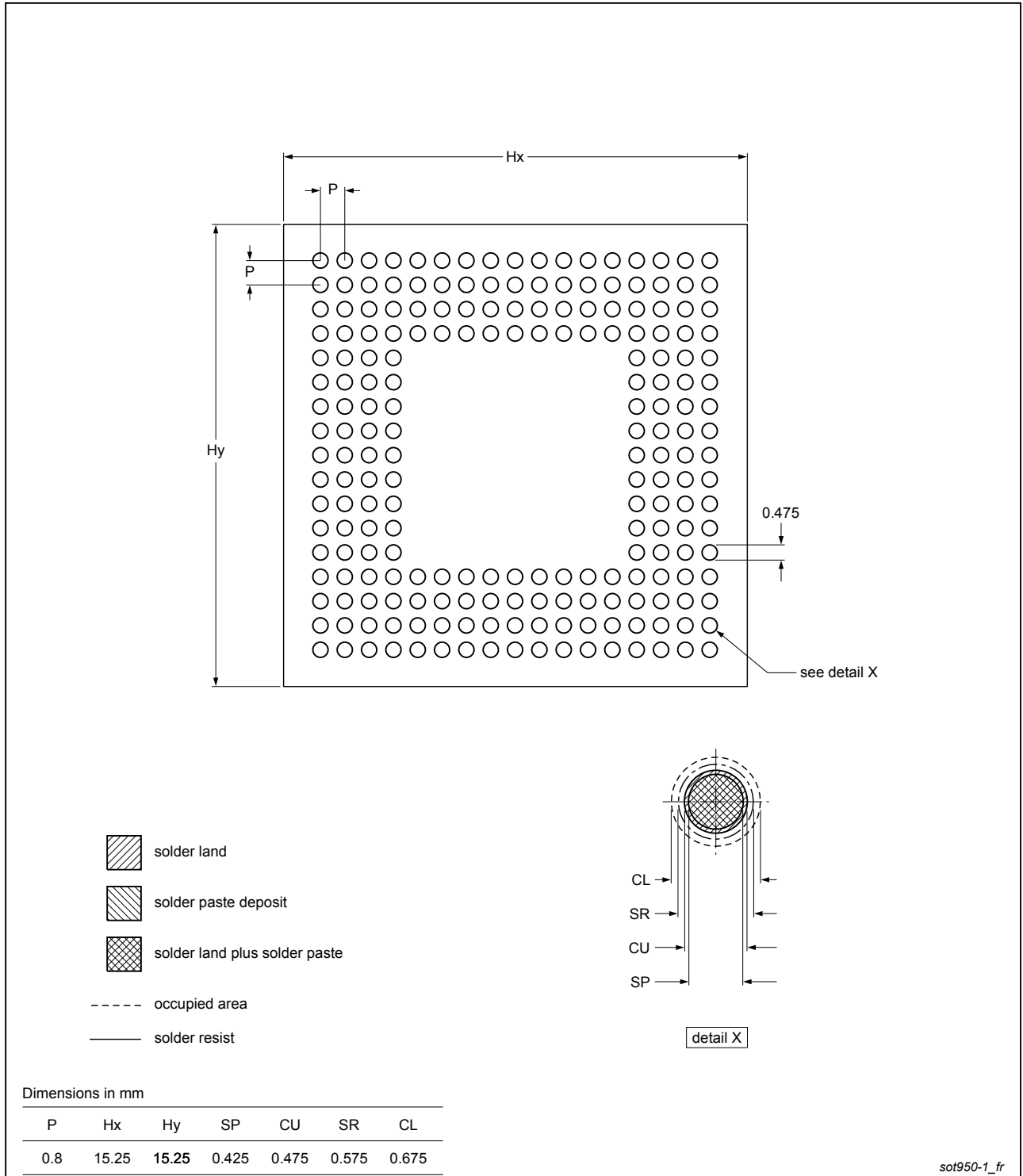


Fig. 2. Reflow soldering footprint for TFBGA208 (SOT950-1)

4. Legal information

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